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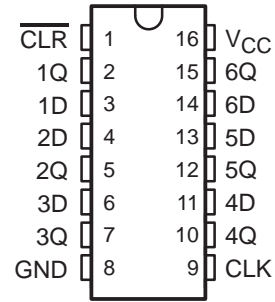
Jameco Part Number 835032

# SN74F174A HEX D-TYPE FLIP-FLOP WITH CLEAR

SDFS029B – D2932, MARCH 1987 – REVISED OCTOBER 1993

- Contains Six Flip-Flops With Single-Rail Outputs
- Buffered Clock and Direct Clear Inputs
- Applications Include:
  - Buffer/Storage Registers
  - Shift Registers
  - Pattern Generators
- Fully Buffered Outputs for Maximum Isolation From External Disturbances
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

D OR N PACKAGE  
(TOP VIEW)



## description

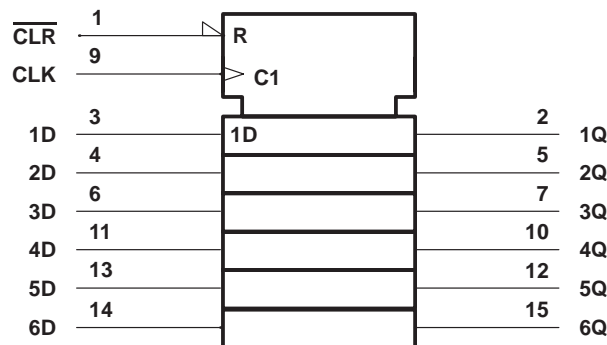
This monolithic, positive-edge-triggered flip-flop utilizes TTL circuitry to implement D-type flip-flop logic with a direct clear (CLR) input. Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output.

The SN74F174A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
CLR	CLK	D	Q
H	L	X	Q <sub>0</sub>
H	↑	H	H
H	↑	L	L
L	X	X	L

## logic symbol†

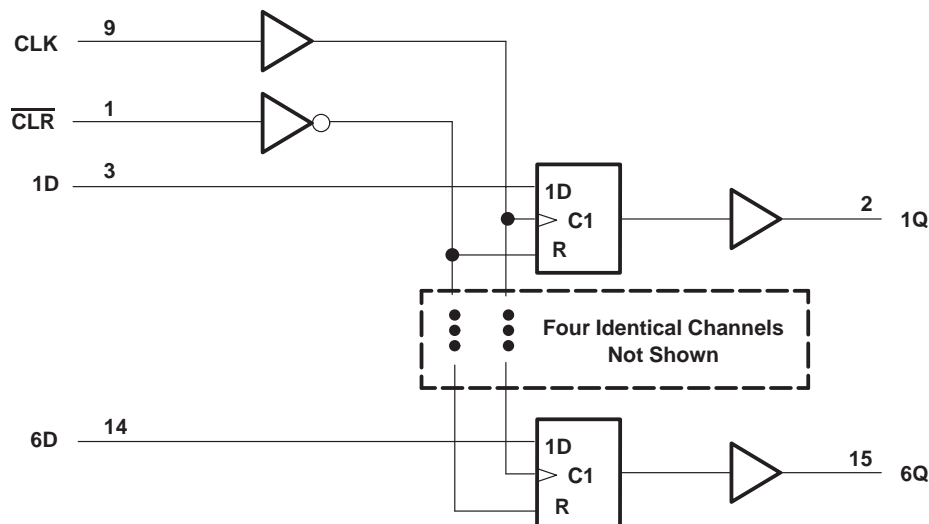


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# SN74F174A HEX D-TYPE FLIP-FLOP WITH CLEAR

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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-1.2 V to 7 V
Input current range .....	-30 mA to 5 mA
Voltage applied to any output in the high state .....	-0.5 V to $V_{CC}$
Current into any output in the low state .....	40 mA
Operating free-air temperature range .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input-voltage ratings may be exceeded provided the input-current ratings are observed.

## recommended operating conditions

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{IK}$	Input clamp current			-18	mA
$I_{OH}$	High-level output current			-1	mA
$I_{OL}$	Low-level output current			20	mA
$T_A$	Operating free-air temperature	0		70	°C

# SN74F174A HEX D-TYPE FLIP-FLOP WITH CLEAR

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V}$ , $I_{OH} = -1\text{ mA}$	2.5	3.4		V
	$V_{CC} = 4.75\text{ V}$ , $I_{OH} = -1\text{ mA}$	2.7			
$V_{OL}$	$V_{CC} = 4.5\text{ V}$ , $I_{OL} = 20\text{ mA}$		0.3	0.5	V
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 7\text{ V}$			0.1	mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 2.7\text{ V}$			20	$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.5\text{ V}$			-0.6	mA
$I_{OS}‡$	$V_{CC} = 5.5\text{ V}$ , $V_O = 0$	-60		-150	mA
$I_{CCH}$	$V_{CC} = 5.5\text{ V}$ , See Note 2		30	45	mA
$I_{CCL}$	$V_{CC} = 5.5\text{ V}$ , See Note 3		39	55	mA

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTES: 2.  $I_{CCH}$  is measured with all outputs open, all data inputs and enable input at 4.5 V, and the clock input at 4.5 V after being momentarily grounded.

3.  $I_{CCL}$  is measured with all outputs open, all data inputs and enable input at 0 V, and the clock input at 4.5 V after being momentarily grounded.

## timing requirements

		$V_{CC} = 5\text{ V}$ , $T_A = 25^\circ\text{C}$		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $T_A = \text{MIN to MAX}§$		UNIT
		MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency	0	100	0	80	MHz
$t_w$	Pulse duration	CLK high	4	4		ns
		CLK low	6	6		
		$\overline{\text{CLR}}$ low	5	5		
$t_{\text{su}}$	Setup time before $\text{CLK}\uparrow$	Data high or low	4.5	4.5		ns
		$\overline{\text{CLR}}$ high¶	5	5		
$t_h$	Hold time after $\text{CLK}\uparrow$	Data high or low	0.5	1		ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

¶ Inactive-state setup time is also referred to as recovery time.

## switching characteristics (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_L = 500\ \Omega$ , $T_A = 25^\circ\text{C}$			$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_L = 500\ \Omega$ , $T_A = \text{MIN to MAX}§$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$f_{\text{max}}$			100	140		80		MHz
$t_{\text{PLH}}$	CLK	Any Q	2.7	4.5	8	2.7	9	ns
$t_{\text{PHL}}$			3.4	4.2	10	3.3	11	
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	Any Q	4.2	6.3	14	4.2	15	ns

NOTE 4: Load circuits and waveforms are shown in Section 1.





**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74F174AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F174ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F174ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F174ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F174AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F174ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F174ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F174ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Mailing Address: Texas Instruments  
Post Office Box 655303 Dallas, Texas 75265